IPC ASSOCIATION OF ELECTRONICS	© Copyright 2005. 1	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under boto international and Pan-American copyright conventions.			inder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and M	Ifg Informati	on	
upplier l	Information								·					
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi											2023-06-08			
Contact Nai	me	Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-En	ıv-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
uthorized	Representative*	Title - Representative			I	Phone - Representative*				Email -	Email - Representative*			
Product-En	ıv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
]	Requester Item Number Mfr Ite		Number			Effective Date Version Manufactur 2023-06-08 MY1		N	Manufacturing Site		Weight*	UOM	Unit Type	
		NCP508MT25TBG 50 MA LDO						IY1	4.998		mg	Each		
Ianufact	turing Proccess Informa	ntion											·	·
Т	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD		J-STD-020 MSL	Rating	Peak Process Body Temperatur		e Max Time at Peak	Tempera	ture Numb	er of Reflow Cyc	cles	
SnAgCu		C	CU Alloy 1			260 C		seconds 3		nds 3				
mments														
<u>vel 1 - max</u>	ximum time at peak temperat	ure during sol	dering is 10-3	30 seconds										
or more in	formation regarding material	l composition	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	led						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the						
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.251	mg	Supplier	Silicon (Si)	7440-21-3		0.251	mg
Die Attach Epoxy	0.167	mg		Epoxy resin	proprietary data		0.0501	mg
			Supplier	Diethylene glycol monoethyl ether acetate	112-15-2		0.0584	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.0584	mg
Lead Frame	0.903	mg	Supplier	Zinc (Zn)	7440-66-6		0.0011	mg
			Supplier	Iron (Fe)	7439-89-6		0.0212	mg
			Supplier	Copper (Cu)	7440-50-8		0.8804	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0003	mg
Mold Compound-Black	3.611	mg		Epoxy resin	proprietary data		0.1697	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.3611	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0036	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.9069	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.1697	mg
Plating	0.012	mg	Supplier	Palladium (Pd)	7440-05-3		0.0007	mg
			В	Nickel (Ni)	7440-02-0		0.0111	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
Wire Bond - Au	0.054	mg	Supplier	Gold (Au)	7440-57-5		0.054	mg